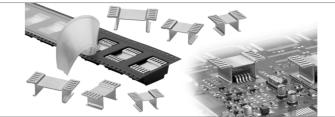
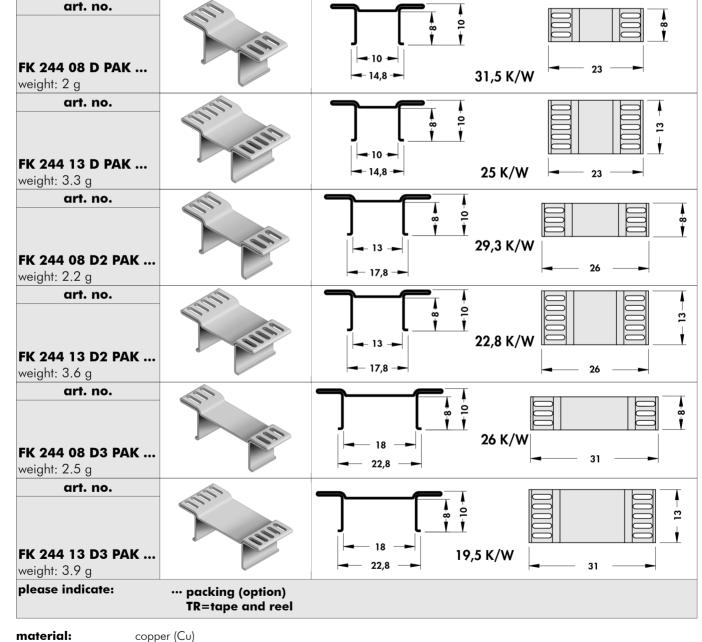
fischer elektronik 23

Heatsinks for **D** PAK and others



- copper heatsinks with excellent heat conductivity
- direct mounting on printed circuit through solderable surface
- especially suitable for SMD components of type D PAK (TO 252), D² PAK (TO 263), D³ PAK (TO 268), SOT 669 LF PAK, SO IC-8 FL MP, Power SO-8, Power SO-10, Power SO-20, Power SO-36, SO-14, SO-16, SOT 223 etc
- available standard packing: loose parts or reel
- special packing like magazine, tray etc. on request
- special versions according to customers specifications
- tape width: 44 mm, reel diameter: 330 mm, quantity: FK 244 08 = 325, FK 244 13 = 200



material: copper (Cu) material thickness: 0.6 mm surface treatment: solderable

Δ

P

E

F

M

C 17

Heatsinks for transistors Heatsinks for TO 5 and TO 18 Attachable heatsinks Finger-shaped heatsinks

High capacity heatsinks Designed parts out of aluminium Heatsink profile-overview Classification table Ν